

Appl. No.: 10/743,527  
Amendment dated March 16, 2006  
Reply to Office Action of December 16, 2005  
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Amendments to the Specification:

On page 8, line 26 through page 9, line 7, please replace the following paragraph:

The conductive layers of each interconnect structure are generally electrically connected in a predefined manner through vias 120 defined by the insulative-coated conductive layers **102**, **114**. In this regard, the vias 120 may be defined, such as by micro-drilling, between the respective conductive layers and the sidewalls of the vias may be electro-plated with a conductive material, such as copper, to establish an electrical connection between the conductive layers. ~~This~~For example, as shown in FIG. 2, the first and second conductive layers **101**, **103** may be selectively connected by means of plated-through vias 120 defined by the first insulative-coated conductive layer **102**. Similarly, the seventh and eighth **113**, **115** conductive layers may be selectively connected by means of plated-through vias 120 defined by the second insulative-coated conductive layer **114**. Likewise, the third, fourth, fifth and sixth conductive layers **105**, **107**, **109**, **111** may be selectively interconnected to one another and/or to the first, second, seventh and eighth conductive layers by vias 120 defined through the respective insulative layers as known to those skilled in the art.

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